DEFENSE LOGISTICS AGENCY
DEFENSE SUPPLY CENTER, COLUMBUS
POST OFFICE BOX 3990
COLUMBUS, OH 43216-5000

IN REPLY
REFER TO

DSCC-VQ (VQC-03-003809/Mr. Thomas/614-692-0587/mjg) 9 December 2003

SUBJECT: Laboratory Suitability for MIL-STD-883, FSC 5962

Mr. Pat McCord
Vice President, Quality Assurance
Austin Semiconductor, Inc.
8701 Cross Park Drive
Austin, TX 78754-4566

Dear Mr. McCord:

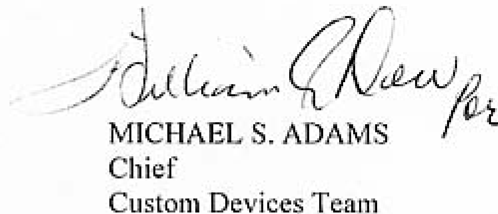
Effective November 5, 2003, the previous Lab Suitability letter, DSCC-VQC-98-083, issued to Austin Semiconductor, Inc. (ASI) by the Defense Supply Center, Columbus (DSCC), is superseded by this letter.

ASI has demonstrated to DSCC compliance with MIL-STD-883, the test standard for integrated circuits. This letter is revised to reflect the current status of ASI's Laboratory Suitability, for the test methods and conditions shown on the enclosure. All testing must be performed in accordance with MIL-PRF-38535 and MIL-STD-883 test methods.

Austin Semiconductor and QPL/QML test labs shall notify the Qualifying Activity immediately after learning of a potential issuance of a GIDEP alert, problem advisory or major quality/reliability problem on their QPL/QML products utilizing test methods listed on the enclosure. Failure to provide prior notification may be grounds for removal from QML-38535.

This Lab Suitability is valid until terminated by written notice from DSCC. If warranted, it may be withdrawn by DSCC at any time. Each of these facilities is subject to an audit by DSCC with minimum notice.

Sincerely,



MICHAEL S. ADAMS
Chief
Custom Devices Team

Enclosure

cc:
DSCC (Michael Grammens)

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TEST	METHOD/ CONDITIONS	Austin Semi.	Millenium Microtech	Amkor Tech.	Atlantic Analytical	Hi-Rel	McKinney Consulting	Wyle Labs
Moisture Resistance	1004	X	X					
Steady State Life Test	1005/A-E	X	X					
Stabilization Bake	1008	X						
Salt Atmosphere	1009/A-D	X	X					
Temperature Cycling	1010/A-F	X	X	X				
Thermal Shock	1011/B,C	X	X					
Seal	1014/A1,B,C	Helium	Krypton	Krypton				
Burn-in	1015/A-F	X	X					
Internal Water Vapor Cont.	1018				X			
Constant Acceleration	2001/A-E	X	X	X				
Mechanical Shock	2002/B	X	X					
Solderability	2003	X	X					
Lead Integrity	2004/B1,B2,D	X	X					
Vibration, Variable Freq.	2007/A	X	X					
External Visual	2009	X	X	X				
Internal Visual	2010/A,B	X	X	B only				
Bond Strength	2011/C,D	X	X	X				
Radiography	2012	X						
Resistance to Solvents	2015	X	X					
Physical Dimensions	2016	X	X	X				
SEM	2018	X				X	X	
Die Shear Strength	2019 & 2027	X	X	X				
PIND	2020/A,B	X	X	X		X		
Nondestructive Bond Pull	2023	X	X	X				
Lid Torque	2024	X						
Adhesion of Lead Finish	2025	X						
Substrate Attach Strength	2027	X	X	X				
Pin Grid Package Destructive Lead Pull Test	2028	X						
Ultrasonic Die Attach Insp.	2030	X						
ESDS	3015							X
Electrical Test	Paragraph 4.5	X	X					